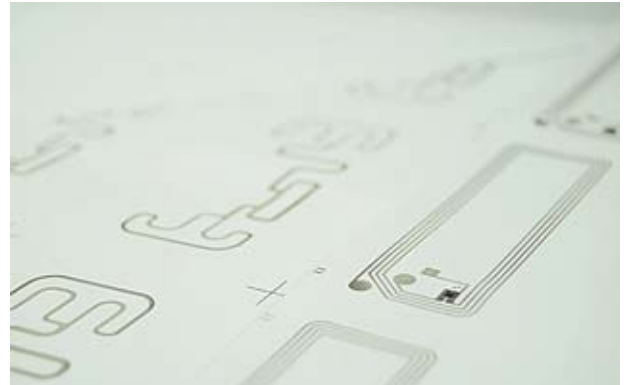


Teslin® Prelaminate

ISO 18000-6c

- High card surface quality without dents and dimples and good printability
- Based on Flip-Chip technology with KSW Palladium Bumping
- Consistent reproducible antenna geometries and read range



Applications

eGovernment

eID cards, eDrivers license, border control

Specifications

Product thickness	approx. 550µm	Integrated Circuit	Impinj Monza 4 family
Substrate	Teslin®, white		
Antenna	conductive silver ink		(Chip alternatives upon request)
Operating frequency	860 to 928MHz	Delivery form	all common card industry formats max. sheet format 56up

Features and Options

Reliability: acc. to ISO 10373-1

For further information please contact the KSW Sales or Customer Service Team:
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